

CLEAN VERSION OF NEW CLAIMS

Claim 21. An optical integrated circuit, comprising:
a tape having a conductive pattern disposed on a surface thereof;

a die mounted to the tape and electrically coupled to the conductive pattern for providing an electronic function of the integrated circuit;

means surrounding the die and bonded to the tape for providing support;

means mounted over the die for allowing an optically active surface of the die to be accessible through the means mounted over the die; and

a plurality of external contacts electrically coupled to the conductive pattern for providing an electrical interface to the die.

Claim 22. The optical integrated circuit of Claim 21, wherein the means surrounding the die is a thin metal support structure having an aperture for accepting the die.

Claim 23. The optical integrated circuit of Claim 21, wherein the means surrounding the die is a thin epoxy film.

Claim 24. The optical integrated circuit of Claim 21, wherein the means mounted over the die is bonded to the die by an optically transparent adhesive to form an integrated covered die, and further comprising an encapsulant disposed between the means surrounding and the covered die.

Claim 25. The optical integrated circuit of Claim 21, wherein the means mounted over the die is bonded to a top surface of the means surrounding the die.

Claim 26. The optical integrated circuit of Claim 21, wherein the means mounted over the die is a glass cover.